Bluetooth 5.1 Dual Mode Module



### **General Description**

BDE-BDM209A is a Bluetooth 5.1 BR/EDR & BLE Dual Mode module.

The module offers a unique combination of Bluetooth classic and Bluetooth Low Energy radio TI's CC2564C and an ARM 32-bit Cortex-M4F CPU MSP432, with integration of all external components including antenna at a very affordable cost.

The module provides the best-in-class RF performance with transmit power and

receive sensitivity that provides twice the range and higher throughput than other Bluetooth-low-energyonly solutions. The power-management hardware and software algorithms provide significant power savings in all commonly used Bluetooth BR/EDR and low energy modes of operation.

The certified and royalty free Dual-mode Bluetooth 4.2 protocol stack software provides a complete Bluetooth BR/EDR, and Bluetooth Low Energy sample applications that reduce design effort and ensure a faster time to market.

### **Key Features**

- Processing and memories
  - Arm<sup>®</sup> 32-bit Cortex<sup>®</sup>-M4F CPU with floating point unit and memory protection unit
  - Frequency up to 48 MHz
  - 256KB flash main memory (organized into two banks enabling simultaneous read or execute during erase)
  - ▶ 16KB of flash information memory
  - 64KB of SRAM (including 6KB of backup memory)
  - > 32KB of ROM with MSP432<sup>™</sup> peripheral driver libraries
- Bluetooth 5.1 Declaration ID D049226
- BR and EDR Features Include:
  - Up to Seven Active Devices
  - Scatternet: Up to Three Piconets Simultaneously, One as Master and Two as Slaves
  - Up to Two Synchronous Connection Oriented (SCO) Links on the Same Piconet
  - Support for All Voice Air-Coding— Continuously Variable Slope Delta (CVSD), A-Law, μ-Law, and Transparent (Uncoded)
  - Assisted Mode for HFP 1.6 Wideband Speech (WBS) Profile or A2DP Profile to Reduce Host Processing and Power
  - Support of Multiple Bluetooth Profiles with Enhanced QoS

- Bluetooth Low Energy Features Include:
  - Support of up to 10 Simultaneous Connections
  - Multiple Sniff Instances Tightly Coupled to Achieve Minimum Power Consumption
  - Independent Buffering for Low Energy Allows Large Numbers of Multiple Connections Without Affecting BR or EDR Performance
  - Built-In Coexistence and Prioritization Handling for BR, EDR, and Low Energy
- Best-in-Class Bluetooth (RF) Performance (TX Power, RX Sensitivity, Blocking)
  - Class 1.5 TX Power up to +10 dBm
  - ➢ −93 dBm Typical RX Sensitivity
  - Internal Temperature Detection and Compensation to Ensure Minimal Variation in RF Performance Over Temperature, No External Calibration Required
  - Improved Adaptive Frequency Hopping (AFH) Algorithm with Minimum Adaptation Time
  - Provides Longer Range, Including Twice the Range of Other Low-Energy-Only Solutions
- Advanced Power Management for Extended Battery Life and Ease of Design
  - Low Power Consumption for Active,



### Bluetooth 5.1 Dual Mode Module



- Standby, and Scan Bluetooth Modes
- Shutdown and Sleep Modes to Minimize Power Consumption
- MCU Ultra-low-power operating modes when Bluetooth is Shutdown
  - Active: 80 μA/MHz
  - Low-frequency active: 83 μA at 128 kHz
  - LPM3 (with RTC): 660 nA
  - LPM3.5 (with RTC): 630 nA
  - LPM4: 500 nA
  - ▶ LPM4.5: 25 nA
- Operating characteristics
  - Wide supply voltage range: 2.05V to 3.7V
  - Temperature range: –40°C to 85°C
- Flexible clocking features
  - Tunable internal DCO (up to 48 MHz)
    - 32.768-kHz low-frequency crystal support (LFXT)
    - ➢ High-frequency crystal support (HFXT) up to 48 MHz
    - > Low-frequency internal reference oscillator (REFO)
    - Very low-power low-frequency internal oscillator (VLO)
  - Module oscillator (MODOSC)
  - System oscillator (SYSOSC)
- Code security features
  - JTAG and SWD lock
  - IP protection (up to four secure flash zones, each with configurable start address and size)
- Enhanced system features
  - Programmable supervision and monitoring of supply voltage
  - Multiple-class resets for better control of application and debug
  - RTC with calendar and alarm functions
- Timing and control
  - Up to four 16-bit timers, each with up to five capture, compare, PWM capability
  - Two 32-bit timers, each with interrupt generation capability
- Physical Interfaces:
  - UART with automatic baud-rate detection
  - I2C (with multiple-slave addressing)
  - SPI (up to 16 Mbps)
  - Up to 17 GPIOs for users
  - > All GPIOs with capacitive-touch

capability

- Ultra-low-leakage I/Os (±20 nA maximum)
- Up to 15 I/Os with interrupt and wake-up capability
- Two I/Os with glitch filtering capability
- Fully Programmable Digital Pulse-Code Modulation (PCM)–I2S Codec Interface
- Antenna: Multilayer Chip Antenna or U.FL connector
- Encryption and data integrity accelerators
  - 128-, 192-, or 256-bit AES encryption and decryption accelerator
  - 32-bit hardware CRC engine
- Bluetooth 4.2 Dual-mode stack
  - dual-mode Bluetooth 4.2 certified and royalty free
  - Fully qualified Bluetooth stack (QDID 85355 and QDID 69886)
- Classic Bluetooth Profiles Available
  - A2DP1.2, AVDTP1.2, AVRCP1.3, HSP1.2, GAP, HID1.0, MAP1.0, PBAP1.0, RFCOMM, SDP, SPP.
- Bluetooth low energy Profiles Available
  - ANS1.0, BAS1.0, CSCS1.0, DIS1.0, FMP1.0, GAPS1.0, GATT1.0, HTS1.0, HRS1.0, HIDS1.0, IAS1.0, LLS1.0, PASS1.0, PXP1.0, TPS1.0.
- MFi Support
  - iAP Protocol (iAP 1/iAP 2) provided as an add-on upon request
- Packaging
  - 12 mm x 22 mm x 2.1 mm package
- Large variety of Sample Applications
  - Classic Bluetooth Sample Applications include: A3DP Sink/Source, HFP, HID, HSP, MAP, PBAP, SPP application demos.
  - BLE Sample Applications include: ANP, iBeacon, HRP, HTP, PASP, HOGP, PXP, FMP, CSCP application demos.
  - Classic Bluetooth + Bluetooth low energy Sample Applications include: SPP+SPPLE, SPP DMMulti application demos.
- Development Environment supports:
  - CCS, Keil<sup>®</sup>, and IAR Embedded Workbench<sup>®</sup> IDEs.
  - Standards Conformance
  - BQB
    - ETSI EN 300 328 and EN 300 440 Class 2 (Europe)
    - FCC CFR47 Part 15 (US)

Bluetooth 5.1 Dual Mode Module



# **Applications**

- Mobile Accessories
- Sports and Fitness Applications
- Wireless Audio Solutions
- Set-Top Boxes and Remote Controls
- Toys
- Test and Measurement
- Industrial: Cable Replacement
- Wireless Sensors
- Automotive Aftermarket
- Wellness and Health

Bluetooth 5.1 Dual Mode Module



# Contents

| General Description                   | 1 |
|---------------------------------------|---|
| Key Features                          | 1 |
| Applications                          | 3 |
| Contents                              | 4 |
| 1. References                         | 5 |
| 2. Block Diagram                      | 6 |
| 3. Pinout                             | 7 |
| 4. Characteristics                    |   |
| 4.1. Absolute Maximum Ratings         |   |
| 4.2. Recommended Operating Conditions |   |
| 4.3. Device Characteristics           |   |
| 5. Mechanical Specifications          |   |
| 5.1. Dimensions                       |   |
| 5.2. PCB Footprint                    |   |
| 6. Ordering Information               |   |
| 7. FCC Warning                        |   |
| 8. FCC Statements                     |   |
| 9. IC Statements                      |   |
| Revision History                      |   |

Bluetooth 5.1 Dual Mode Module



### 1. References

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- [2]. MSP432P401R/MSP432P401M SimpleLink<sup>™</sup> Mixed-Signal Microcontrollers Datasheet, Texas Instruments.

https://www.ti.com/lit/gpn/msp432p401r

[3]. CC2564C Dual-mode Bluetooth<sup>®</sup> stack on MSP432<sup>™</sup> microcontroller unit (MCU) User's Guide, Texas Instruments. <u>https://www.ti.com/lit/ug/swru453b/swru453b.pdf?ts=1603868491588&ref\_url=https%253A%252F</u>

<u>%252Fwww.google.com%252F</u>

Bluetooth 5.1 Dual Mode Module



# 2. Block Diagram

BDM209A is highly integrated System on Module Bluetooth Dual-mode device that comprises of TI's CC2564C Bluetooth Dual-mode controller, MSP432 ARM 32-bit Cortex-M4F MCU, a high-performance chip antenna and peripherals.

TBD Figure 1: BDM209A Module Block Diagram

### Bluetooth 5.1 Dual Mode Module



### 3. Pinout





| Table | 1: | Pin | Description |
|-------|----|-----|-------------|
| IUNIC |    |     | Description |

| Pin # | Pin Name |            | Туре          | Reset<br>State | Description   |
|-------|----------|------------|---------------|----------------|---|
| 1     | GND      |            | GND           | N/A            | Ground  |
| 2     | GND      |            | GND           | N/A            | Ground  |
| 3     | GND      |            | GND           | N/A            | Ground  |
| 4     | VDD      |            | GND           | N/A            | 3.3V DC voltage supply  |
| 5     | P2.1     | P2.1       | DIO           | OFF            | General-purpose digital I/O with port<br>interrupt and wake-up capability and<br>with reconfigurable port mapping<br>secondary function. This I/O can be<br>configured for high drive operation with<br>up to 20-mA drive capability. |
|       |          | PM_UCA1CLK |               | N/A            | eUSCI_A1 clock input/output (direction controlled by eUSCI)   |
| 6     | VDD      |            | PWR           | N/A            | 3.3V DC voltage supply  |
| 7     | AUD_CLK  |            | DIO, HY, 4 mA | PD             | PCM clock, Fail-safe  |
| 8     | AUD_IN   |            | DI, 4 mA      | PD             | PCM data input, Fail-safe   |

### Bluetooth 5.1 Dual Mode Module



Datasheet

| Pin # | Pin Name  |             | Туре      | Reset<br>State | Description  |
|-------|-----------|-------------|-----------|----------------|--|
| 9     | P2.2      | P2.2        | DIO       | OFF            | General-purpose digital I/O with port<br>interrupt and wake-up capability and<br>with reconfigurable port mapping<br>secondary function. This I/O can be<br>configured for high drive operation with<br>up to 20-mA drive capability.    |
|       |           | PM_UCA1RXD  | DI        | N/A            | eUSCI_A1 UART RXD (direction controlled by eUSCI – input)  |
|       |           | PM_UCA1SOMI | DIO       | N/A            | eUSCI_A1 SPI slave out master in (direction controlled by eUSCI)   |
| 10    | AUD_FSYNC |             | DIO, 4 mA | PD             | PCM frame sync, Fail-safe  |
| 11    | AUD_OUT   |             | DO, 4 mA  | PD             | PCM data output, Fail-safe   |
| 12    | P3.0      |             | DIO       | OFF            | General-purpose digital I/O with port<br>interrupt, wakeup, and glitch filtering<br>capability.  |
| 13    | P1.7      | P1.7        | DIO       | OFF            | General-purpose digital I/O with port interrupt and wake-up capability   |
|       |           | UCBOSCL     |           | N/A            | I2C clock – eUSCI_B0 I2C mode  |
| 14    | P1.6      | P1.6        | DIO       | OFF            | General-purpose digital I/O with port interrupt and wake-up capability   |
|       |           | UCBOSDA     |           | N/A            | I2C data – eUSCI_B0 I2C mode   |
| 15    | P2.3      | P2.3        | DIO       | OFF            | General-purpose digital I/O with port<br>interrupt and wake-up capability and<br>with reconfigurable port mapping<br>secondary function. This I/O can be<br>configured for high drive operation with<br>up to 20-mA<br>drive capability. |
|       |           | PM_UCA1TXD  | DO        | N/A            | eUSCI_A1 UART TXD (direction controlled by eUSCI – output)   |
|       |           | PM_UCA1SIMO | DIO       | N/A            | eUSCI_A1 SPI slave in master out<br>(direction controlled by eUSCI)  |
| 16    | P4.0      | P4.0        | DIO       | OFF            | General-purpose digital I/O with port interrupt and wake-up capability   |
|       |           | A13         | AI        | N/A            | ADC analog input A13   |
| 17    | P2.0      | P2.0        | DIO       | OFF            | General-purpose digital I/O with port<br>interrupt and wake-up capability and<br>with reconfigurable port mapping<br>secondary function. This I/O can be<br>configured for high drive operation with<br>up to 20-mA drive capability.    |
|       |           | PM_UCA1STE  |           | N/A            | eUSCI_A1 SPI slave transmit enable (direction controlled by eUSCI)   |
|       |           | P5.7        | DIO       | OFF            | General-purpose digital I/O with port interrupt and wake-up capability   |
| 18    | P5.7      | TA2.2       | DIO       | N/A            | TA2 CCR2 capture: CCI2A input, compare: Out2   |
|       |           | VREF-       | AO        | N/A            | Internal shared reference voltage  |

BDE Technology Inc.

### Bluetooth 5.1 Dual Mode Module



Datasheet

| Pin # | Pin Name  |          | Туре | Reset<br>State | Description   |  |  |
|-------|-----------|----------|------|----------------|---|--|--|
|       |           |          |      |                | negative terminal   |  |  |
|       |           | VeREF-   | AI   | N/A            | Negative terminal of external reference<br>voltage to ADC (recommended to<br>connect to onboard ground) |  |  |
|       |           | C1.6     | AI   | N/A            | Comparator_E1 input 6   |  |  |
|       |           | P5.6     | DIO  | OFF            | General-purpose digital I/O with port interrupt and wake-up capability                                  |  |  |
|       |           | TA2.1    | DIO  | N/A            | TA2 CCR1 capture: CCl1A input, compare: Out1  |  |  |
| 19    | P5.6      | VREF+    | AO   | N/A            | Internal shared reference voltage<br>positive terminal  |  |  |
|       |           | VeREF+   | AI   | N/A            | Positive terminal of external reference voltage to ADC  |  |  |
|       |           | C1.7     | AI   | N/A            | Comparator_E1 input 7   |  |  |
| 20    | P6.1      | P6.1     | DIO  | OFF            | General-purpose digital I/O with port interrupt and wake-up capability                                  |  |  |
|       |           | A14      | DI   | N/A            | ADC analog input A14  |  |  |
| 24    | DCT       | nRST     | 51   | PU             | External reset (active low)   |  |  |
| 21    | nRST      | NMI      | וט   | N/A            | External nonmaskable interrupt  |  |  |
|       |           | P1.2     | DIO  | OFF            | General-purpose digital I/O with port interrupt and wake-up capability                                  |  |  |
| 22    | P1.2      | UCA0RXD  | DI   | N/A            | Receive data – eUSCI_A0 UART mode   |  |  |
|       |           | UCA0SOMI | DIO  | N/A            | Slave out, master in – eUSCI_A0 SPI<br>mode   |  |  |
|       |           | P1.3     | DIO  | OFF            | General-purpose digital I/O with port interrupt and wake-up capability                                  |  |  |
| 23    | P1.3      | UCA0TXD  | DO   | N/A            | Transmit data – eUSCI_A0 UART mode  |  |  |
|       |           | UCA0SIMO | DIO  | N/A            | Slave in, master out – eUSCI_AO SPI<br>mode   |  |  |
| 24    | TDO       | TDO      | DO   | N /A           | JTAG test data output   |  |  |
| 24    | IDO       | SWO      | DO   | N/A            | Serial wire trace output  |  |  |
|       |           | PJ.5     | DIO  |                | General-purpose digital I/O   |  |  |
| 25    | SWCI KTCK | ТСК      |      | PD             | JTAG clock input (TCK)  |  |  |
|       |           | SWCLK    |      |                | Serial wire clock input (SWCLK)   |  |  |
| 26    | трі       | TDI      | DI   | PU             | JTAG test data input  |  |  |
|       |           | PJ.4     | DIO  | N/A            | General-purpose digital I/O   |  |  |
| 27    | SWDIOTMS  | TMS      | DIO  | PU             | JTAG test mode select (TMS)   |  |  |
|       |           | SWDIO    | _    |                | Serial wire data input/output (SWDIO)   |  |  |
| 20    | 54.0      | P1.0     | DIO  | OFF            | General-purpose digital I/O with port<br>interrupt, wakeup, and glitch filtering<br>capability          |  |  |
| 28    | P1.0      | UCA0STE  |      | N/A            | Slave transmit enable – eUSCI_A0 SPI<br>mode  |  |  |
| 20    |           |          | DO   |                | CC2564C Internal dobug massages   |  |  |
| 29    | IV_DRG    |          |      |                | General-purpose digital I/O with port   |  |  |
| 30    | P1.1      | P1.1     | DIO  | OFF            | interrupt, wakeup, and glitch filtering capability  |  |  |



Datasheet

#### Bluetooth 5.1 Dual Mode Module

| Pin # | Pin Name |         | Туре | Reset<br>State | Description  |
|-------|----------|---------|------|----------------|--|
|       |          | UCA0CLK |      | N/A            | Clock signal input – eUSCI_AO SPI slave<br>mode<br>Clock signal output – eUSCI_AO SPI<br>master mode |
| 31    | GND      |         | GND  |                | Ground   |

1. Type:

DIO = Digital Input-Output, DI = Digital Input, DO = Digital Output, AI = Analog Input, AO = Analog Output, PWR = Power, GND = Ground, HY = Input Hysteresis, x mA = Typical output current.

- 2. Reset States:
  - OFF = High-impedance with Schmitt trigger and pullup or pulldown (if available) disabled
  - PD = High-impedance input with pulldown enabled
  - PU = High-impedance input with pullup enabled
  - N/A = Not applicable
- 3. For detail information, please refer to <u>References</u>.

#### Table 2. Connection for Unused Pins

| PIN          | POTENTIAL   | COMMENT  |
|--------------|-------------|--|
| Px.0 to Px.7 | Open        | Set to port function in output direction, and leave unconnected.   |
| RSTn/NMI     | DVCC or VCC | 47-kΩ pullup with 1.1-nF pulldown.   |
| PJ.4/TDI     | Open        | The JTAG TDI pin is shared with general-purpose I/O function (PJ.4). If not being used, this pin should be set to port function in the output direction. When used as JTAG TDI pin, it should remain open.                       |
| PJ.5/TDO/SWO | DVCC or VCC | The JTAG TDO/SWO pin is shared with general-purpose I/O function (PJ.5). If not being used, this pin should be set to port function in the output direction. When used as JTAG TDO/SWO pin, it should be pulled down externally. |
| SWDIOTMS     | DVCC or VCC | This pin should be pulled up externally.   |
| SWCLKTCK     | DVSS or VSS | This pin should be pulled down externally.   |
| TX_DUG       | Open        | Remain open.   |

1. For any unused pin with a secondary function that is shared with general-purpose I/O, follow the guidelines for the Px.0 to Px.7 pins. Refer to <u>References</u>.

Bluetooth 5.1 Dual Mode Module



### 4. Characteristics

All MIN/MAX specification limits are guaranteed by design, production testing and/or statistical characterization. Typical values are based on characterization results at default measurement conditions and are informative only.

Default measurement conditions (unless otherwise specified): VDD= 3.0 V, TA = 25  $^{\circ}$ C. All radio measurements are performed with standard RF measurement equipment.

### 4.1. Absolute Maximum Ratings

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

#### Table 3: Absolute Maximum Ratings

| Parameter        | Description                      | Conditions | Min  | Max  | Unit |
|------------------|----------------------------------|------------|------|------|------|
| VDD              | Power Supply voltage at VDD pins |            | -0.3 | 4.17 | V    |
| T <sub>STG</sub> | Storage temperature              |            | -40  | 125  | °C   |

### 4.2. Recommended Operating Conditions

#### Table 4: Recommended Operating Conditions

| Parameter           | Description                      | Conditions | Min  | Тур | Max | Unit |
|---------------------|----------------------------------|------------|------|-----|-----|------|
| VDD                 | Power supply voltage             |            | 2.05 | 3.0 | 3.7 | V    |
| Т                   |                                  |            | -40  |     | 85  | °C   |
| I <sub>INRUSH</sub> | Inrush current into the VDD pins |            |      |     | 100 | mA   |

### 4.3. Device Characteristics

#### Table 5: Digital IO - Recommended Operating Conditions

| Parameter | Description                            | Conditions    | Min     | Тур | Max   | Unit |
|-----------|--|---------------|---------|-----|---|------|
| VIT+      | Positive-going input threshold voltage | VDD = 3V      | 1.35    |     | 2.25  | V    |
| VIT-      | Negative-going input threshold voltage | VDD = 3V      | 0.75    |     | 1.65  | V    |
| Vон       | High-level output voltage              | VDD = 3V,     | VDD-0.6 |     | VDD   | V    |
|           |  | IOHmax = -6MA |         |     | Max           2.25           1.65           VDD           VSS+0.6 |      |
| Vo        |  | VDD = 3V,     | 1/55    |     |   |      |
| VOL       |  | IOLmax = 6mA  | V33     |     | V33+0.0   |      |

#### Table 6: Radio for Bluetooth BR EDR - Recommended Operating Conditions

| Parameter | Description         | Conditions  | Min  | Тур    | Max  | Unit |
|-----------|---------------------|-------------|------|--------|------|------|
| foper     | Operating frequency |             | 2402 |        | 2480 | MHz  |
| Nсн       | Number of channels  |             |      | 79     |      | 1    |
| Fсн       | Channel frequency   | K = 0 to 78 |      | 2402+K |      | MHz  |

#### Table 7: Radio for Bluetooth Low Energy - Recommended Operating Conditions



Datasheet

### Bluetooth 5.1 Dual Mode Module

| Parameter | Description         | Conditions  | Min  | Тур      | Max  | Unit |
|-----------|---------------------|-------------|------|----------|------|------|
| foper     | Operating frequency |             | 2402 |          | 2480 | MHz  |
| Nсн       | Number of channels  |             |      | 40       |      | 1    |
| Fсн       | Channel frequency   | K = 0 to 39 |      | 2402+K*2 |      | MHz  |

#### Table 8: RF - AC Characteristics

| Parameter | Description                     | Conditions          | Min | Тур   | Max | Unit |
|-----------|---------------------------------|---------------------|-----|-------|-----|------|
| ТХбғѕк    | Maximum RF output               | CLER                |     | 12    |     | dBm  |
|           | Power - GFSK                    | GFSK                |     |       |     |      |
| TXedr     | Maximum RF output               |                     |     | 10    |     | dBm  |
|           | Power - EDR                     | EDK                 |     |       |     |      |
| RXsen_1   | RX sensitivity - GFSK           | GFSK, BER = 0.1%    |     | -95   |     | dBm  |
| RXsen_2   | RX sensitivity - $\pi$ /4-DQPSK | π <b>/4-DQPSK</b> , |     | 04 5  |     | dBm  |
|           |                                 | BER = 0.01%         |     | -94.5 |     |      |
| RXsen_3   | RX sensitivity - DPSK           | 8DPSK, BER =        |     | 07 5  |     | dBm  |
|           |                                 | 0.01%               |     | -87.5 |     |      |

# 5. Mechanical Specifications

### 5.1. Dimensions

The module dimensions are presented in the following figure:



Figure 3: Mechanical Drawing

Bluetooth 5.1 Dual Mode Module



# 5.2. PCB Footprint

The footprint for the PCB is presented in the following figure:





# 6. Ordering Information

#### Table 11: Ordering Information

| Part Number | Size (mm)     | Shipping Form | MOQ  |
|-------------|---------------|---------------|------|
| BDE-BDM209A | 12 x 22 x 2.4 | Tape & Reel   | 1000 |

### 7. FCC Warning

Integration instructions for host product manufacturers according to KDB 996369 D03 OEM Manual v01

**1. List of applicable FCC rules** FCC Part 15.247

#### 2. Specific operational use conditions

This transmitter/module and its antenna(s) must not be co-located or operating in conjunction with any transmitter. This information also extends to the host manufacturer's instruction manual.

#### 3. Limited module procedures

Not applicable

#### 4. Trace antenna designs

It is "not applicable" as trace antenna which is not used on the module.

#### 5. RF exposure considerations

This equipment complies with FCC RF radiation exposure limits set forth for an uncontrolled environment. This compliance to FCC radiation exposure limits for an uncontrolled environment, and minimum of 20cm separation between antenna and body.

The host product manufacturer would provide the above information to end users in their end-product manuals.

#### 6. Antennas

Multilayer Chip Antenna; 0.5dBi; 2400-2500MHz

#### 7. Label and compliance information

The end product must carry a physical label or shall use e-labeling followed KDB784748D01 and KDB 784748 stating "Contains Transmitter Module FCC ID: 2ABRU-BDM209A".

#### 8. Information on test modes and additional testing requirements

For more information on testing, please contact the manufacturer.

#### 9. Additional testing, Part 15 Subpart B disclaimer

The modular transmitter is only FCC authorized for the specific rule parts (FCC Part 15.247) listed on

the grant, and that the host product manufacturer is responsible for compliance to any other FCC

rules that apply to the host not covered by the modular transmitter grant of certification. The final host



### Bluetooth 5.1 Dual Mode Module

product still requires Part 15 Subpart B compliance testing with the modular transmitter installed when contains digital circuity.

### 8. FCC Statements

(OEM) Integrator has to assure compliance of the entire end-product incl. the integrated RF Module. For 15 B (§15.107 and if applicable §15.109) compliance, the host manufacturer is required to show compliance with 15 while the module is installed and operating.

Furthermore the module should be transmitting and the evaluation should confirm that the module's intentional emissions (15C) are compliant (fundamental / out-of-band). Finally the integrator has to apply the appropriate equipment authorization (e.g. Verification) for the new host device per definition in §15.101.

Integrator is reminded to assure that these installation instructions will not be made available to the end-user of the final host device.

The final host device, into which this RF Module is integrated" has to be labeled with an auxiliary label stating the FCC ID of the RF Module, such as "Contains FCC ID: 2ABRU-BDM209A

"This device complies with part 15 of the FCC rules. Operation is subject to the following two conditions: (1)this device may not cause harmful interference, and

(2)this device must accept any interference received, including interference that may cause undesired operation."

"Changes or modifications to this unit not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment."

The Integrator will be responsible to satisfy SAR/ RF Exposure requirements, when the module integrated into the host device.

#### Module statement

The single-modular transmitter is a self-contained, physically delineated, component for which compliance can be demonstrated independent of the host operating conditions, and which complies with all eight requirements of § 15.212(a)(1) as summarized below.

1) The radio elements have the radio frequency circuitry shielded.

2) The module has buffered modulation/data inputs to ensure that the device will complywith Part 15 requirements with any type of input signal.

3) The module contains power supply regulation on the module.

4) The module contains a permanently attached antenna.

5) The module demonstrates compliance in a stand-alone configuration.

6) The module is labeled with its permanently affixed FCC ID label.

7) The module complies with all specific rules applicable to the transmitter, including all the conditions provided in the integration instructions by the grantee.



### Bluetooth 5.1 Dual Mode Module

8) The module complies with RF exposure requirements.

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help

### 9. IC Statements

The final host device, into which this RF Module is integrated" has to be labeled with an auxiliary label stating the IC of the RF Module, such as" Contains transmitter module IC: 25657-BDM209A Le périphériquehôte final, danslequelce module RF estintégré "doitêtreétiqueté avec

uneétiquetteauxiliaireindiquant le CI du module RF, tel que" Contient le module émetteur IC: 25657-BDM209A

This device contains licence-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's licence-exempt RSS(s). Operation is subject to the following two conditions:

(1) This device may not cause interference.

(2) This device must accept any interference, including interference that may cause undesired operation of the device.

L'émetteur/récepteur exempt de licencecontenudans le présentappareilestconforme aux CNR d'Innovation, Sciences et Développementéconomique Canada applicables aux appareils radio exempts de licence. L'exploitationestautorisée aux deux conditions suivantes :

(1) L' appareil ne doit pas produire de brouillage;

(2) L' appareildoit accepter tout brouillageradioélectriquesubi, mêmesi le brouillageest susceptible d' encompromettre le fonctionnement.

RF Exposure Warning Statements:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment shall be installed and operated with minimum distance 20cm between the radiator & body.

Radio Frequency Exposure Statement for IC:



Datasheet

### Bluetooth 5.1 Dual Mode Module

The device has been evaluated to meet general RF exposure requirements. The device can be used in mobile exposure conditions. The min separation distance is 20cm.

Déclaration d'exposition aux radiofréquences pour IC:

L'appareil a été évalué pour répondre aux exigences générales en matière d'exposition aux RF. L'appareil peut être utilisé dans des conditions d'exposition mobiles. La distance de séparation minimale est de 20 cm.

## **10. TELEC Label**

Product Name: Bluetooth 5.1 Dual Mode Module Part Number: BDE-BDM209A



XXX-XXXXXX

## **Revision History**

| Revision | Date             | Description                              |
|----------|------------------|--|
| V0.9     | 20-October-2020  | Preliminary version                      |
| V1.0     | 30-October-2020  | Formal Release version.                  |
| V1.1     | 28-December-2020 | Add Bluetooth 5.1 Declaration ID D049226 |
| V1.2     | 3-January-2021   | Updated device photo                     |